

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
ON APPEAL FROM THE EXAMINER TO THE BOARD  
OF PATENT APPEALS AND INTERFERENCES**

In re Application of: Mark T. McCormack et al.  
Serial No.: 09/866,092  
Filing Date: May 23, 2001  
Group Art No.: 2815  
Confirmation No.: 5484  
Examiner: Eugene Lee  
Title: *Structure and Method for Embedding Components  
In Multi-Layer Substrates*

**Mail Stop Appeal Brief - Patents**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**REQUEST FOR STATUS**

The above-identified patent application is currently on appeal before the Board of Patent Appeals and Interferences. Applicants received an Answer in response to the Appeal Brief filed on February 15, 2008. Applicants filed a Reply Brief on August 14, 2008. Since mailing the Reply Brief to the Board, Applicants have not heard anything further regarding this application. Accordingly, Applicants respectfully request status of the present application, and in particular request notice of the approximate date on which the Board expects to issue a decision in this appeal.

If there are any matters that can be cleared up through a telephone conversation, please contact the undersigned attorney for Applicants, Brian W. Oaks, at 214.953.6986.

Respectfully submitted,  
BAKER BOTTS L.L.P.  
Attorneys for Applicants



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Brian W. Oaks  
Reg. No. 44,981

Dated: March 13, 2009

Customer No. **05073**